

MOSFET MODULE Dual 30A 450V/500V

PD4M441L / PD4M440L

FEATURES

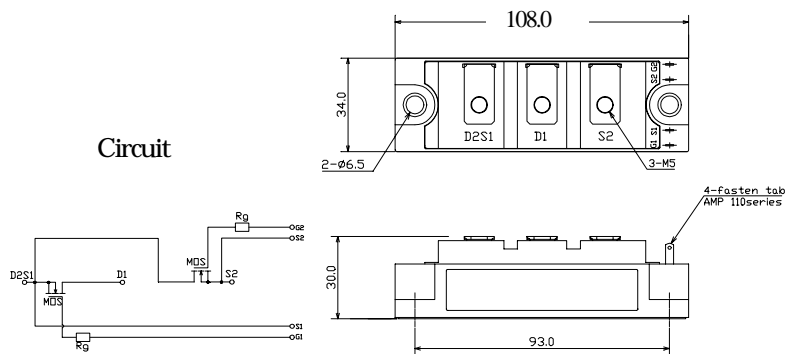
- * Dual MOS FETs Cascaded Circuit
- * Low On-Resistance and Switching Dissipation

TYPICAL APPLICATIONS

- * Power Supply for the Communications and the Induction Heating

OUTLINE DRAWING

Dimension(mm)



Approximate Weight : 220g

MAXMUM RATINGS

Ratings		Symbol	PD4M441L	PD4M440L	Unit
Drain-Source Voltage ($V_{GS}=0V$)		V_{DSS}	450	500	V
Gate - Source Voltage		V_{GSS}	+/- 20		V
Continuous Drain Current	Duty=50%	I_D	30 ($T_c=25^\circ C$)		A
	D.C.		21 ($T_c=25^\circ C$)		
Pulsed Drain Current		I_{DM}	60 ($T_c=25^\circ C$)		A
Total Power Dissipation		P_D	230 ($T_c=25^\circ C$)		W
Operating Junction Temperature Range		T_{jw}	-40 to +150		$^\circ C$
Storage Temperature Range		T_{sg}	-40 to +125		$^\circ C$
Isolation Voltage (Terminals to Base AC, 1 min.)		V_{ISO}	2000		V
Mounting Torque	Module Base to Heatsink	F_{TOR}	3.0		N•m
	Bus Bar to Main Terminals		2.0		

ELECTRICAL CHARACTERISTICS (@ $T_c=25^\circ C$ unless otherwise noted)

Characteristic	Symbol	Test Condition	Min.	Typ.	Max.	Unit
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS}=V_{DSS}, V_{GS}=0V$	-	-	1.0	mA
		$T_j=125^\circ C, V_{DS}=V_{DSS}, V_{GS}=0V$	-	-	4.0	
Gate-Source Threshold Voltage	$V_{GS(th)}$	$V_{DS}=V_{GS}, I_D=1mA$	2.0	3.2	4.0	V
Gate-Source Leakage Current	I_{GSS}	$V_{GS}=\pm 20V, V_{DS}=0V$	-	-	1.0	μA
Static Drain-Source On-Resistance	$r_{DS(on)}$	$V_{GS}=10V, I_D=15A$	-	190	210	m-ohm
Forward Transconductance	g_{fs}	$V_{DS}=15V, I_D=15A$	-	27	-	S
Input Capacitance	C_{ies}	$V_{DS}=25V, V_{GS}=0V, f=1MHz$	-	5.2	-	nF
Output Capacitance	C_{oss}		-	1.1	-	nF
Reverse Transfer Capacitance	C_{rss}		-	0.18	-	nF
Turn-On Delay Time	$t_{d(on)}$	$V_{DD}=1/2V_{DSS}$	-	100	-	ns
Rise Time	t_r	$I_D=15A$	-	60	-	
Turn-Off Delay Time	$t_{d(off)}$	$V_{GS}=-5V, +10V$	-	180	-	
Fall Time	t_f	$R_C=70\Omega$	-	50	-	

FREE WHEELING DIODES RATINGS & CHARACTERISTICS ($T_c=25^\circ C$)

Characteristic	Symbol	Test Condition	Min.	Typ.	Max.	Unit
Continuous Source Current	I_S	D.C.	-	-	21	A
Pulsed Source Current	I_{SM}	-	-	-	60	A
Diode Forward Voltage	V_{SD}	$I_S=30A$	-	-	2.0	V
Reverse Recovery Time	t_{rr}	$I_S=30A, -dis/dt=100A/\mu s$	-	750	-	ns
Reverse Recovery	Q_r		-	17	-	μC

THERMAL CHARACTERISTICS

Characteristic	Symbol	Test Condition	Min.	Typ.	Max.	Unit
Thermal Resistance, Junction to Case	$R_{th(j-c)}$	MOS FET	-	-	0.56	$^\circ C/W$
		Diode	-	-	0.56	
Thermal Resistance, Case to Heatsink	$R_{th(c-h)}$	Mounting surface flat, smooth, and greased	-	-	0.1	$^\circ C/W$

PD4M44xL

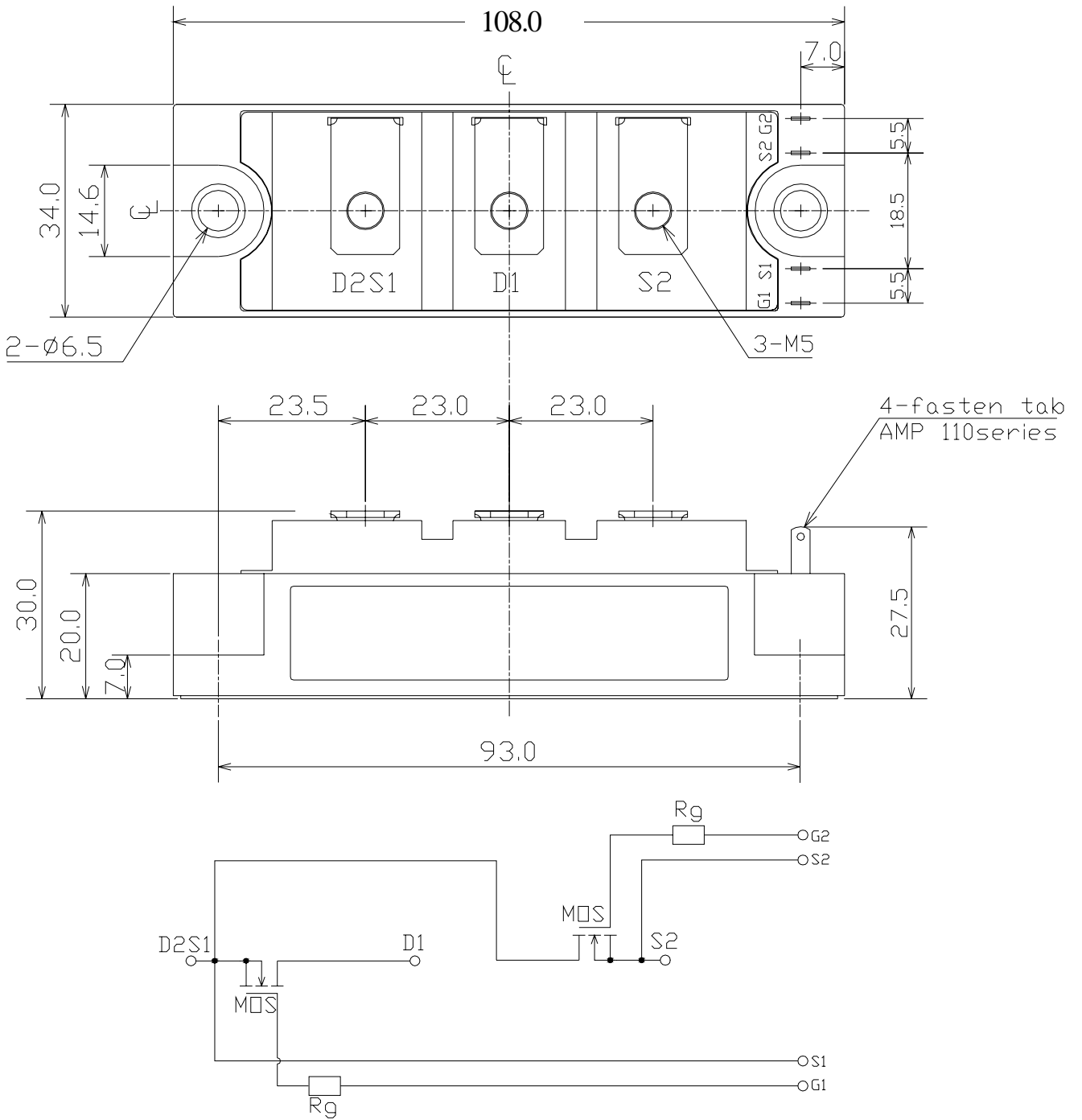


Fig.1- Output Characteristics (Typical)

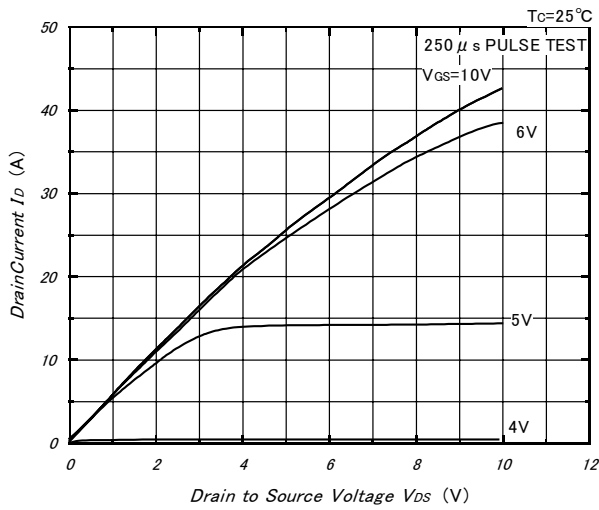


Fig.2- Drain to Source On Voltage vs. Gate to Source Voltage (Typical)

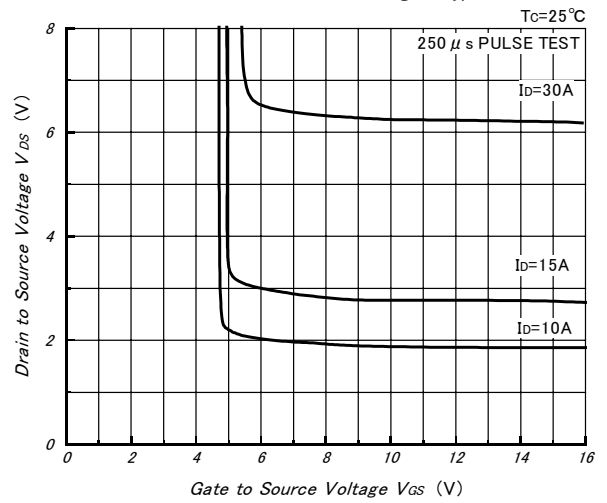


Fig.3- Drain to Source On Voltage vs. Junction Temperature (Typical)

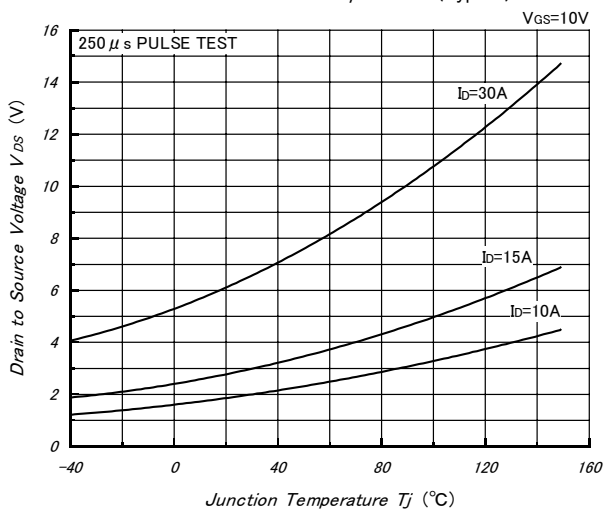


Fig.4- Capacitance vs. Drain to Source Voltage (Typical)

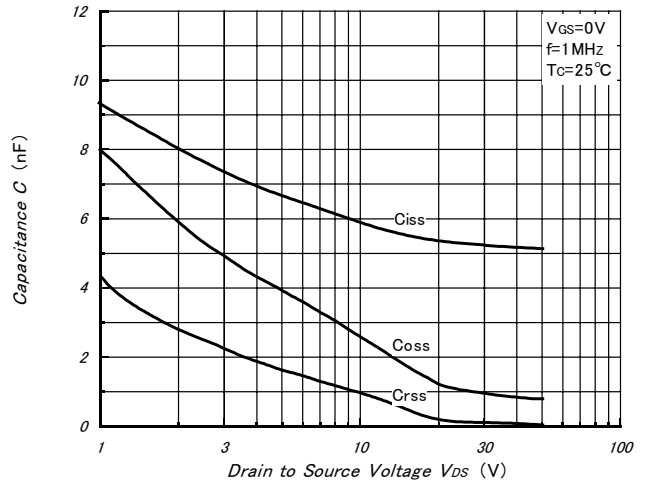


Fig.5- Gate Charge vs. Gate to Source Voltage (Typical)

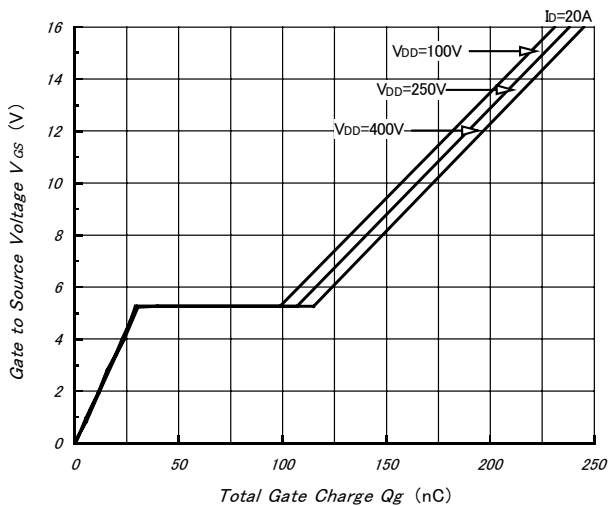


Fig.6- Series Gate Impedance vs. Switching Time (Typical)

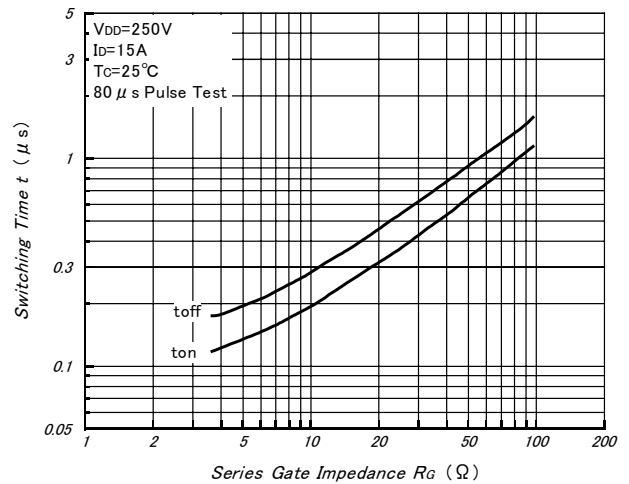


Fig.7- Drain Current vs. Switching Time (Typical)

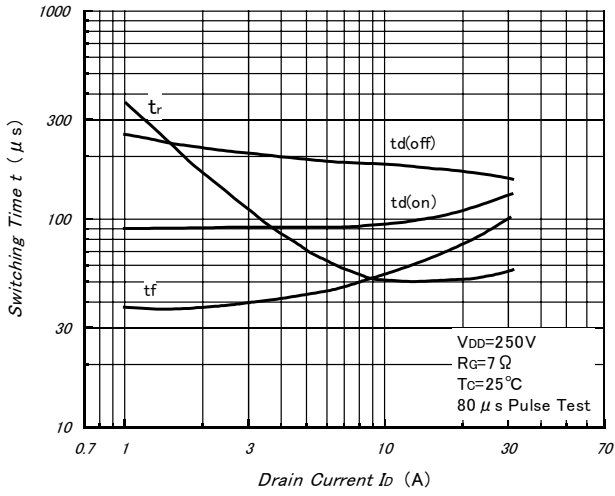


Fig.8- Source to Drain Diode Forward Characteristics (Typical)

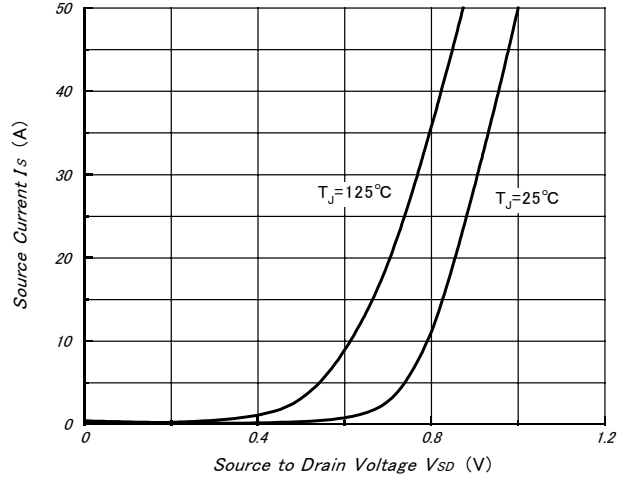


Fig.9- Reverse Recovery Characteristics (Typical)

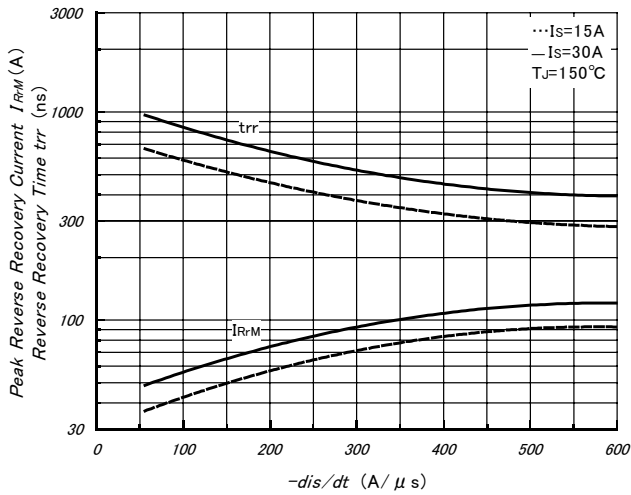


Fig.10- Maximum Safe Operating Area

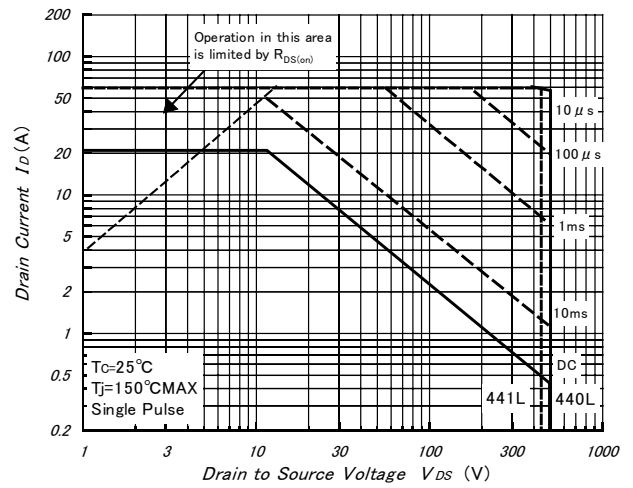


Fig.11- Normalized Transient Thermal Impedance (MOSFET)

